AMENDMENTS TO THE CLAIMS:

1. (Currently Amended) A light emitting apparatus, comprising:

a semiconductor light emitting element including a substrate, wherein light [[that]] radiates [[light]] from a light emission surface ~~provided on a~~ of the substrate of said light emitting element, the light emission surface being provided on the substrate opposite to an electrode forming surface of ~~said light emitting element;~~ the substrate; and

~~lead frames that are electrically connected to electrodes formed on the electrode forming surface through wires;~~

a transparent structure ~~that is~~ mounted on the light emission surface of the substrate, wherein the transparent structure is [[and]] optically connected with the light emission surface and has a light distribution characteristic based on [[its]] a three-dimensional shape of the transparent structure. ~~shape; and~~

~~light transmitting resin that seals the semiconductor light emitting element and the transparent structure.~~

2. (Original) The light emitting apparatus according to claim 1, wherein:

the transparent structure has a length in the horizontal direction greater than that of the semiconductor light emitting element.

3. (Original) The light emitting apparatus according to claim 1, wherein:

the transparent structure has a thickness of half that of the semiconductor light emitting element to twice the length of a shorter side of the semiconductor light emitting element.

4. (Original) The light emitting apparatus according to claim 1, wherein:

the transparent structure has a microscopic uneven surface to diffuse light.

5. (Original) The light emitting apparatus according to claim 1, wherein:

the transparent structure has a reflection layer formed on its surface.

6. (Currently Amended) The light emitting apparatus according to claim [[1]] 17, wherein:

one of the lead frames has a cup portion, and

the transparent structure is fixed on the cup portion through adhesive resin with light diffusion material mixed therein.

7. (Currently Amended) The light emitting apparatus according to claim [[1]] 17, wherein:

the electrodes do not transmit light.

8. (Currently Amended) A light emitting apparatus, comprising:

a semiconductor light emitting element that includes a substrate and that radiates light from a light emission surface provided on [[a]] the substrate of the semiconductor light emitting element opposite an electrode forming surface of the substrate;

lead frames that are electrically connected to electrodes formed on the electrode forming surface through wires;

a transparent structure that is mounted on the light emission surface of the substrate and optically connected with the light emission surface and has a light distribution characteristic based on [[its]] a three-dimensional shape of the transparent structure; and

light transmitting resin that seals the semiconductor light emitting element and the transparent structure, the light transmitting resin including a phosphor to wavelength-convert light emitted from the semiconductor light emitting element.

9. (Original) The light emitting apparatus according to claim 8, wherein:

the light transmitting resin contains two or more kinds of phosphors.

10. (Previously Presented) The light emitting apparatus according to claim 1, wherein the semiconductor light emitting element comprises the substrate, a buffer layer, an n-type semiconductor layer, a light-emitting layer, and a p-type semiconductor layer.

11. (Previously Presented) The light emitting apparatus according to claim 1, wherein the semiconductor light emitting element comprises a gallium nitride system compound semiconductor.

12. (Previously Presented) The light emitting apparatus according to claim 1, wherein the transparent structure comprises a light transmitting material comprising at least one of SiO_2, Al_2O_3, SiC, Si_3N_4, AlN, ZrO_2, borosilicate glass, and alumino-silicate glass.

13. (Previously Presented) The light emitting apparatus according to claim 1, wherein the substrate comprises sapphire.

14. (Currently Amended) The light emitting apparatus according to claim 1, wherein the transparent structure is ~~mounted on~~ bonded to the substrate by an adhesive layer.

15. (Previously Presented) The light emitting apparatus according to claim 14, wherein the adhesive layer comprises a transparent adhesive.

16. (Currently Amended) A light emitting apparatus, comprising:

a semiconductor light emitting element that includes a substrate and that radiates light from a light emission surface provided on [[a]] the substrate of the semiconductor light emitting element opposite to an electrode forming surface of ~~said light emitting element~~; the substrate;

lead frames that are electrically connected to electrodes formed on the electrode forming surface through wires;

a transparent structure that is mounted on the light emission surface of the substrate and optically connected with the light emission surface and has a light distribution characteristic based on [[its]] a three-dimensional shape of the transparent structure; and

light transmitting resin that seals the semiconductor light emitting element and the transparent structure,

wherein the transparent structure has a length in the horizontal direction greater than that of the semiconductor light emitting element.

17. (New) The light emitting apparatus according to claim 1, further comprising lead frames that are electrically connected to electrodes formed on the electrode forming surface through wires.

18. (New) The light emitting apparatus according to claim 1, further comprising light transmitting resin that seals the semiconductor light emitting element and the transparent structure.

19. (New) The light emitting apparatus according to claim 8, wherein the transparent structure is mounted on the light emission surface of the substrate by an adhesive layer.

20. (New) The light emitting apparatus according to claim 16, wherein the transparent structure is mounted on the light emission surface of the substrate by an adhesive layer.